MBR0520LT1G, SBR80520LT1G, MBR0520LT3G, SBR80520LT3G

Preferred Devices

Surface Mount Schottky Power Rectifier

Plastic SOD−123 Package

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop−reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package. These state−of−the−art devices have the following features:

Features

- Guardring for Stress Protection
- Very Low Forward Voltage (0.38 V Max @ 0.5 A, 25°C)
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- AEC−Q101 Qualified and PPAP Capable
- SBR8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb−Free*

Mechanical Characteristics

- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
  - ♦ Human Body Model = 3B
  - ♦ Machine Model = C

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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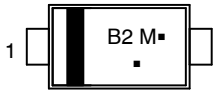
http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 0.5 AMPERES, 20 VOLTS



SOD−123
CASE 425
STYLE 1

MARKING DIAGRAM



B2 = Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MBR0520LT1G	SOD−123 (Pb−Free)	3,000 / Tape & Reel **
SBR80520LT1G	SOD−123 (Pb−Free)	3,000 / Tape & Reel **
MBR0520LT3G	SOD−123 (Pb−Free)	10,000 / Tape & Reel ***
SBR80520LT3G	SOD−123 (Pb−Free)	10,000 / Tape & Reel ***

** 8 mm Tape, 7” Reel
*** 8 mm Tape, 13” Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	V
Average Rectified Forward Current (Rated V_R, T_L = 90°C)	$I_{F(AV)}$	0.5	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	5.5	A
Storage Temperature Range	T_{stg}	−65 to +150	°C
Operating Junction Temperature	T_J	−65 to +125	°C
Voltage Rate of Change (Rated V_R)	dv/dt	1000	V/μs
ESD Ratings: Machine Model = C Human Body Model = 3B		 > 400 > 8000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance; Junction−to−Ambient (Note 1)	$R_{\theta JA}$	206	°C/W
Thermal Resistance; Junction−to−Lead	$R_{\theta JL}$	150	°C/W

1. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 2)	v_F	T_J = 25°C	T_J = 100°C	V
(i_F = 0.1 Amps) (i_F = 0.5 Amps)		0.300 0.385	0.220 0.330	
Maximum Instantaneous Reverse Current (Note 2)	I_R	T_J = 25°C	T_J = 100°C	mA
(V_R = 10 V) (Rated DC Voltage = 20 V)		75 μA 250 μA	5 mA 8 mA	

2. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

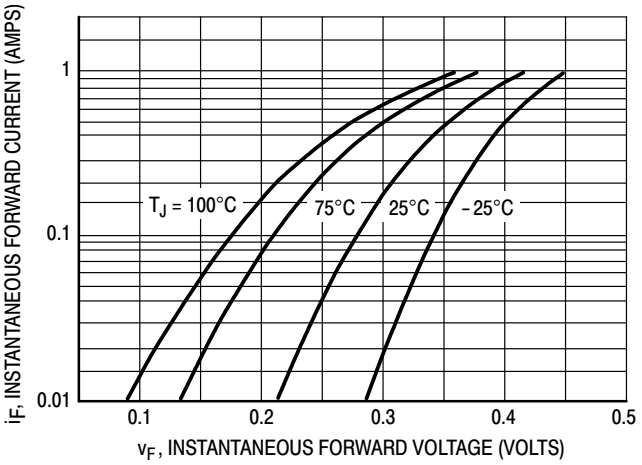


Figure 1. Typical Forward Voltage

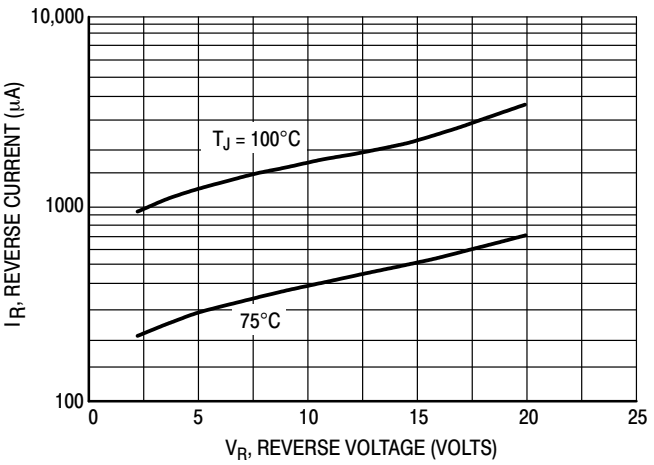


Figure 2. Typical Reverse Current

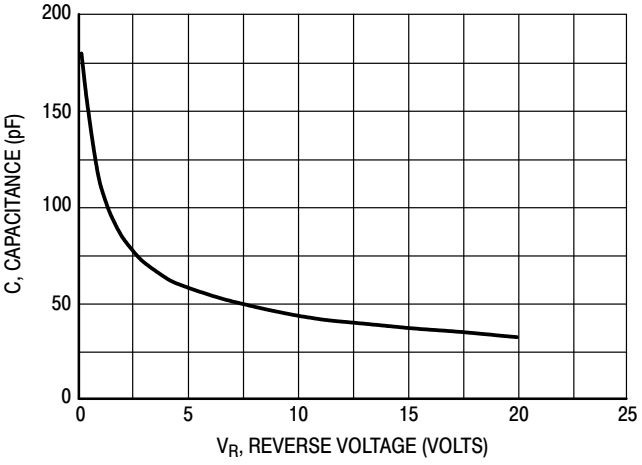


Figure 3. Typical Capacitance

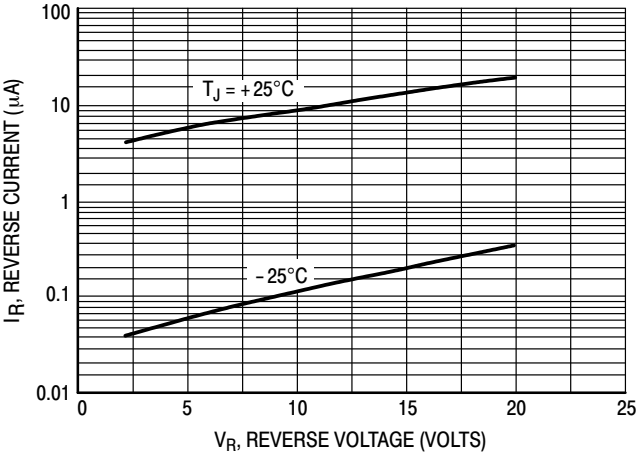


Figure 4. Typical Reverse Current

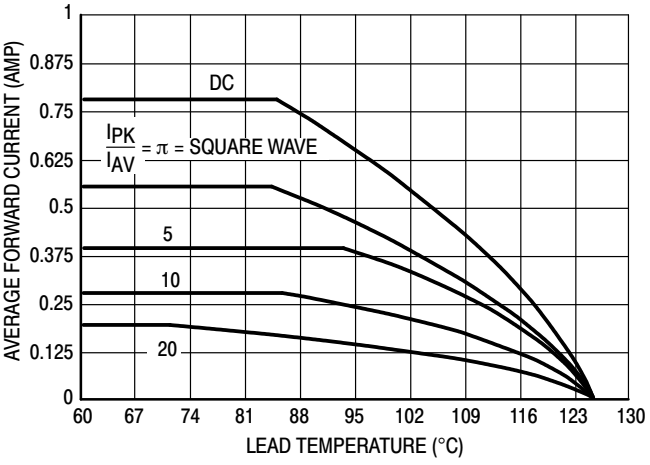


Figure 5. Current Derating (Lead)

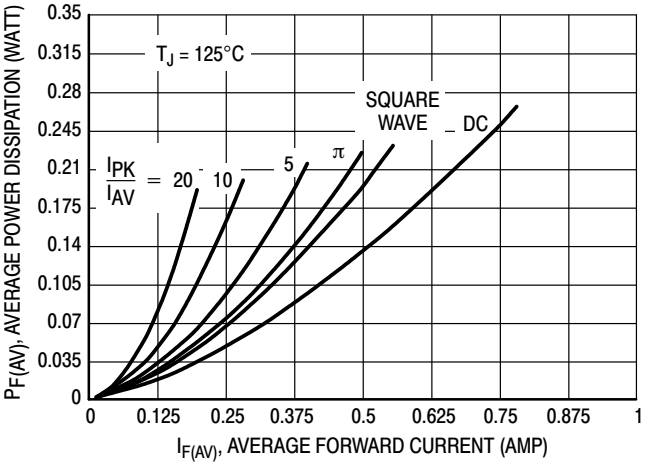


Figure 6. Power Dissipation

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

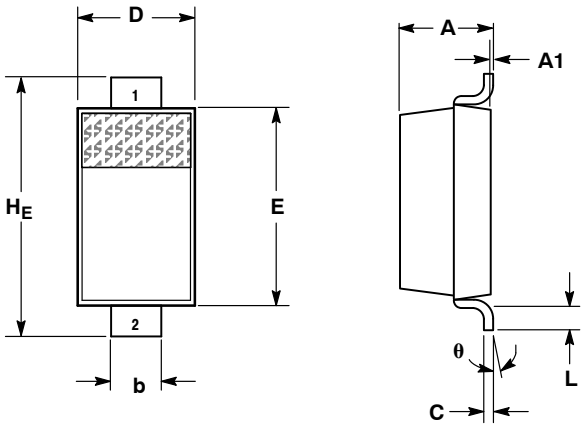
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SCALE 5:1

SOD−123
CASE 425−04
ISSUE G

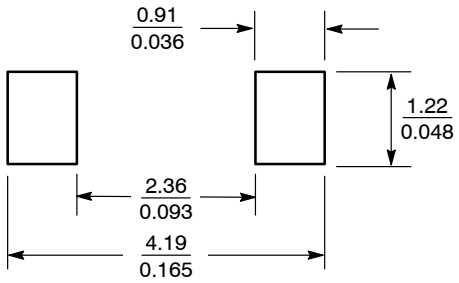
DATE 07 OCT 2009



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
c	---	---	0.15	---	---	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
H_E	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25	---	---	0.010	---	---
θ	0°	---	10°	0°	---	10°

SOLDERING FOOTPRINT*



SCALE 10:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

STYLE 1:
PIN 1. CATHODE
2. ANODE

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DESCRIPTION:	**SOD−123**		**PAGE 1 OF 1**

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